

FIG. 1

008280 69594900

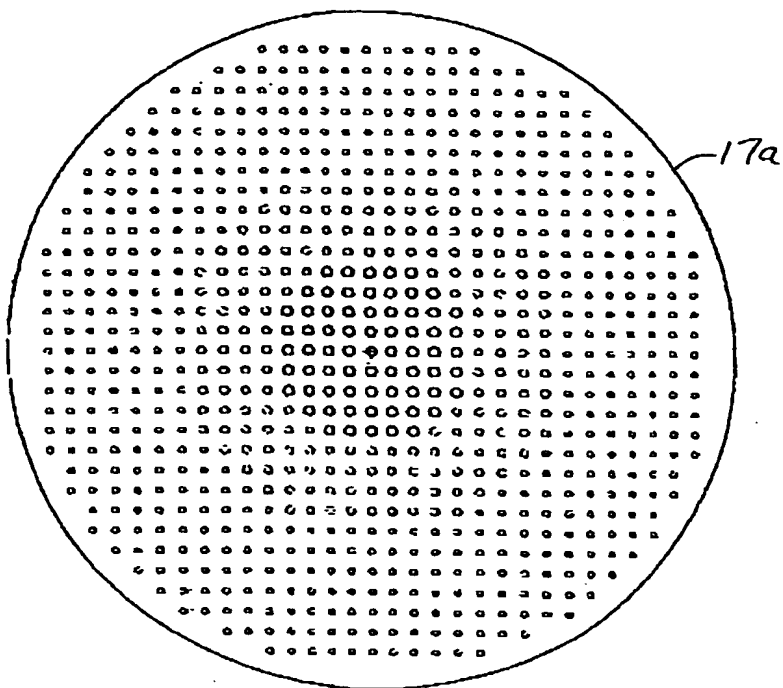


FIG. 2

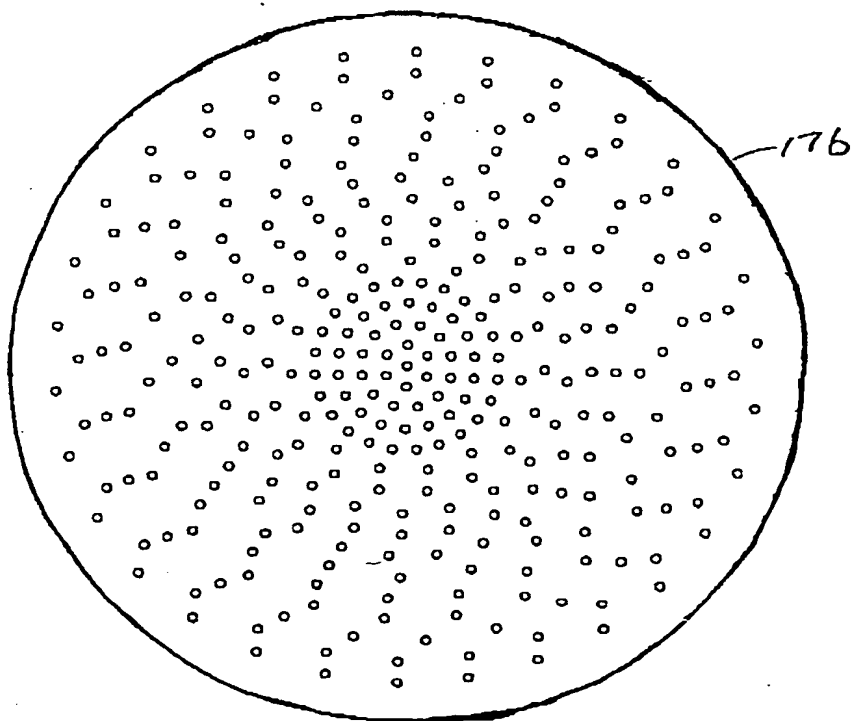


FIG 3.

0034959-08300

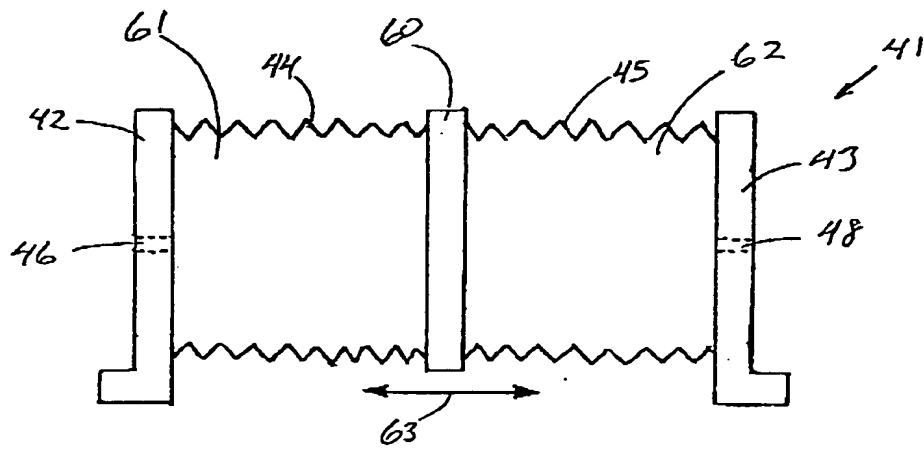


FIG. 4a

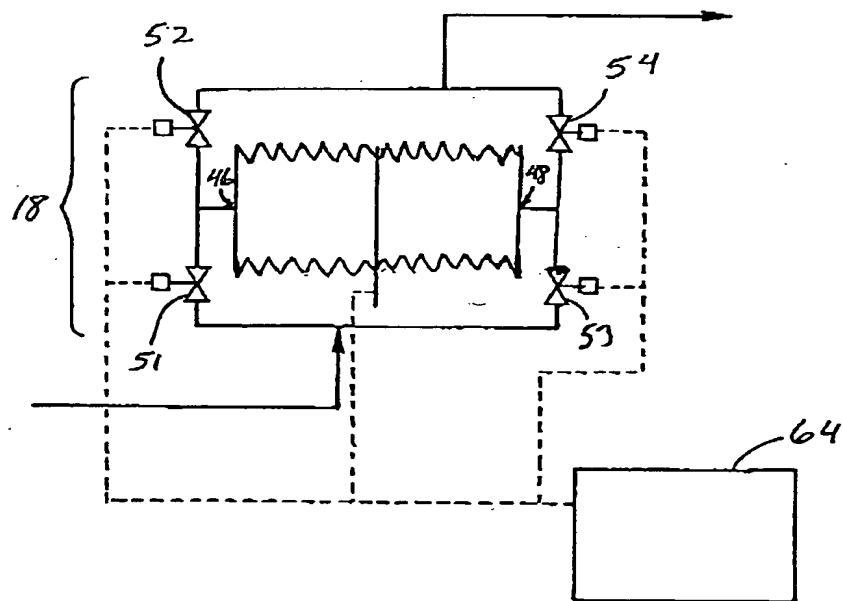


FIG. 4b

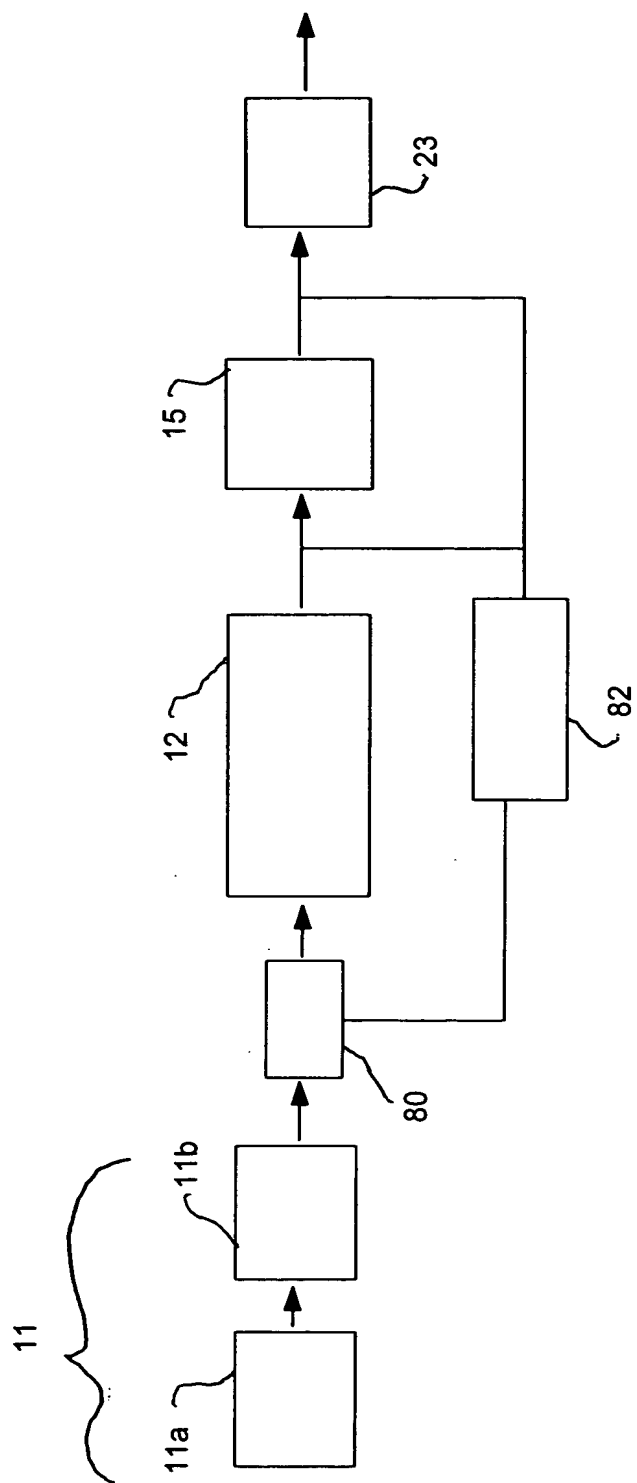


Fig. 5

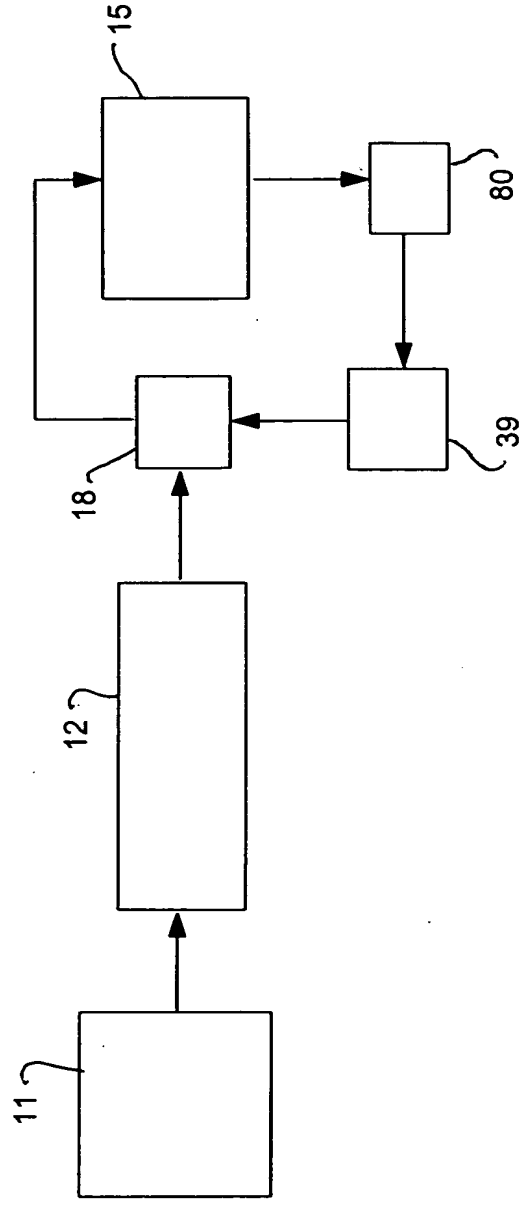


Fig. 6

A cross-sectional view of a semiconductor device 71. The device consists of a substrate 72 with a series of steps or a trench 73. A layer 74 is deposited on the top surface of the substrate. A vertical structure 75, possibly a contact or probe, is formed on the right side of the device. The entire assembly is labeled 71.

FIG. 7